

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









HMC669LP3 / 669LP3E

v04.0709



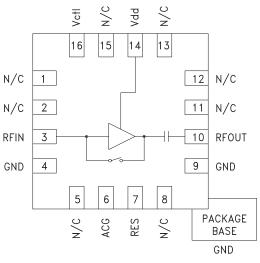
GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

Typical Applications

The HMC669LP3(E) is ideal for:

- Cellular/3G and LTE/WiMAX/4G
- BTS & Infrastructure
- Repeaters and Femtocells
- Tower Mounted Amplifiers
- Test & Measurement Equipment

Functional Diagram



Features

Noise Figure: 1.4 dB Output IP3: +29 dBm

Gain: 17 dB

Failsafe Operation:

Bypass is enabled when LNA is unpowered

Single Supply: +3V or +5V

16 Lead 3x3mm QFN Package: 9 mm²

General Description

The HMC669LP3(E) is a versatile, high dynamic range GaAs MMIC Low Noise Amplifier that integrates a low loss LNA bypass mode on the IC. The amplifier is ideal for receivers and LNA modules operating between 1.7 and 2.2 GHz and provides 1.4 dB noise figure, 17 dB of gain and +29 dBm IP3 from a single supply of +5V @ 86mA. Input and output return losses are excellent and no external matching components are required. A single control line is used to switch between LNA mode and a low loss bypass mode. Failsafe topology also enables the LNA bidirectional bypass path when no DC power is available.

Electrical Specifications, $T_A = +25^{\circ}$ C, Rbias = 15 Ohm

		LNA Mode				Bypass Mode		Failsafe Mode		Units			
Parameter		Vdd = +3V		Vdd = +5V									
	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	
Frequency Range		1.7 - 2.2			1.7 - 2.2			1.7 - 2.2			1.7 - 2.2		GHz
Gain	12	15		14	17		-3	-2.1		-3	-2.1		dB
Gain Variation Over Temperature		0.015			0.014			0.0008			0.0008		dB / °C
Noise Figure		1.4	1.65		1.4	1.65							dB
Input Return Loss		10			11			12			12		dB
Output Return Loss		13			13			12			12		dB
Reverse Isolation		28			30			-			-		dB
Power for 1dB Compression (P1dB) ^[1]		11.5			12			21			24		dBm
Third Order Intercept (IP3)[2]		25			29			25			25		dBm
Supply Current (Idd)		49	59		86	105		0.04			-		mA
Switching Speed													
LNA Mode to Bypass Mode Bypass Mode to LNA Mode		100			100			80			-		ns ns

^[1] P1dB for LNA Mode is referenced to RFOUT while P1dB for Bypass and Failsafe Modes are referenced to RFIN.

^[2] IP3 for LNA Mode is referenced to RFOUT while IP3 for Bypass and Failsafe Modes are referenced to RFIN.

HMC669* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS 🖳

View a parametric search of comparable parts.

EVALUATION KITS

- HMC669LP3 Evaluation Board
- Two Channels, 2400MHz TDD Application

DOCUMENTATION



Data SheetHMC669 Data Sheet

TOOLS AND SIMULATIONS 🖵

HMC669 S-Parameter

REFERENCE MATERIALS 🖳

Quality Documentation

- Package/Assembly Qualification Test Report: 16L 3x3mm QFN Package (QTR: 11003 REV: 02)
- Package/Assembly Qualification Test Report: LP2, LP2C, LP3, LP3B, LP3C, LP3D, LP3F, LP3G (QTR: 2014-0364)
- Semiconductor Qualification Test Report: PHEMT-D (QTR: 2013-00254)

DESIGN RESOURCES 🖵

- HMC669 Material Declaration
- PCN-PDN Information
- · Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC669 EngineerZone Discussions.

SAMPLE AND BUY 🖵

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK 🖳

Submit feedback for this data sheet.

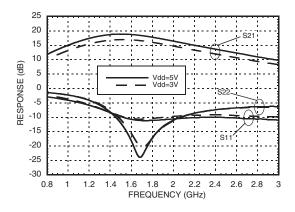
This page is dynamically generated by Analog Devices, Inc., and inserted into this data sheet. A dynamic change to the content on this page will not trigger a change to either the revision number or the content of the product data sheet. This dynamic page may be frequently modified.



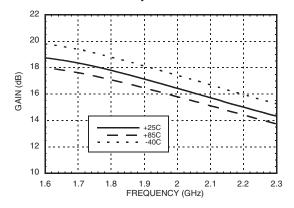


GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

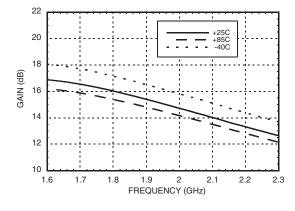
LNA - Broadband Gain & Return Loss



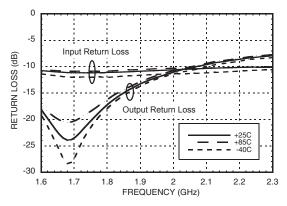
LNA - Gain vs. Temperature [1]



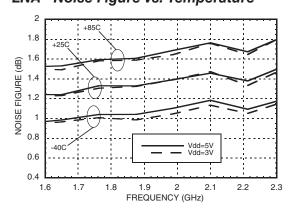
LNA - Gain vs. Temperature [2]



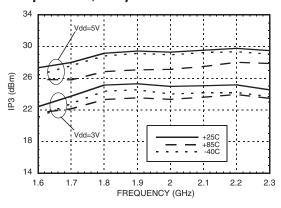
LNA - Return Loss vs. Temperature [1]



LNA - Noise Figure vs. Temperature [3]



LNA - Output IP3 vs.
Temperature, Output Power @ 0 dBm



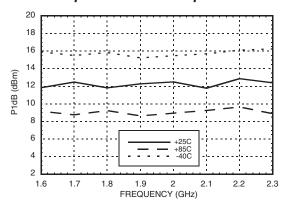
[1] Vdd = 5V [2] Vdd = 3V [3] Measurement reference plane shown on evaluation PCB drawing.



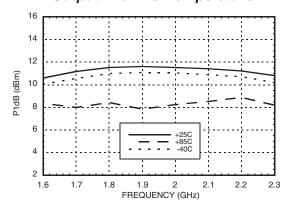


GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

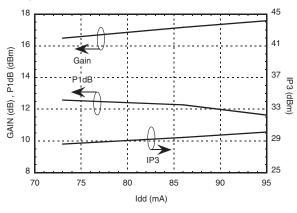
LNA - Output P1dB vs. Temperature [1]



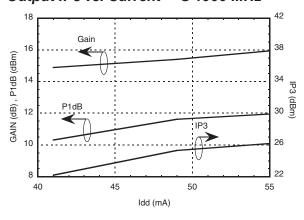
LNA - Output P1dB vs. Temperature [2]



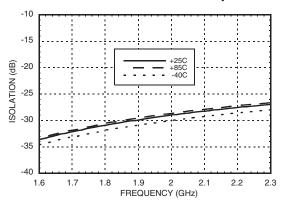
LNA - Gain, P1dB, Output IP3 vs. Current [1] @ 1900 MHz



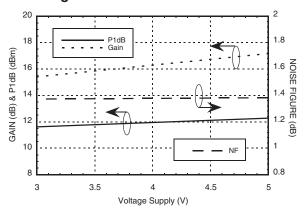
LNA - Gain, P1dB, Output IP3 vs. Current [2] @ 1900 MHz



LNA - Reverse Isolation vs. Temperature [1]



LNA - Output P1dB, Gain & Noise Figure [3] vs. Vdd @ 1900 MHz



[1] Vdd = 5V [2] Vdd = 3V [3] Measurement reference plane shown on evaluation PCB drawing.



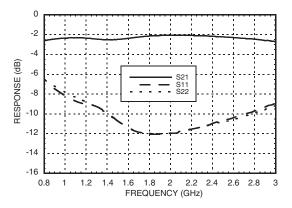
HMC669LP3 / 669LP3E

v04.0709

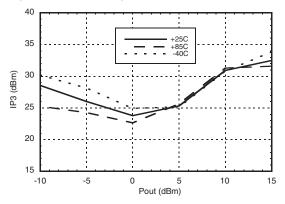


GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

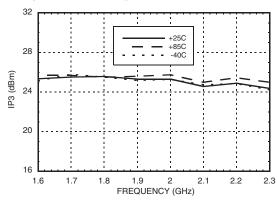
Bypass Mode -Broadband Gain & Return Loss



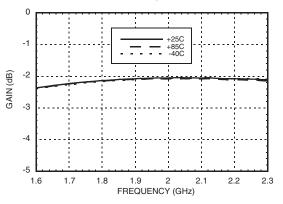
Bypass Mode -Input IP3 vs. Output Power @ 1900 MHz



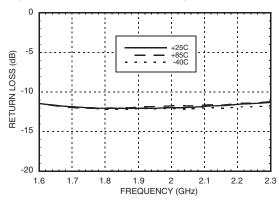
Bypass Mode - Input IP3 vs. Temperature, Output Power @ 5 dBm



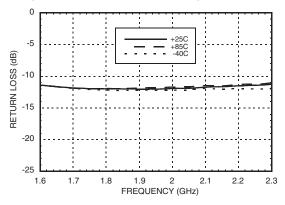
Bypass Mode -Insertion Loss vs. Temperature



Bypass Mode -Input Return Loss vs. Temperature



Bypass Mode -Output Return Loss vs. Temperature



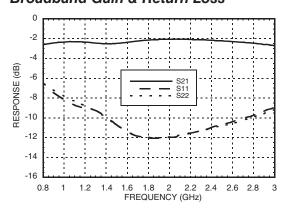
GaAs PHEMT MMIC LNA w/



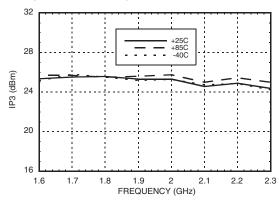
v04.0709



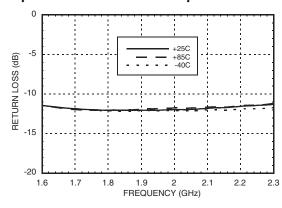
Failsafe Mode -Broadband Gain & Return Loss



Failsafe Mode - Input IP3 vs. Temperature, Output Power @ 5 dBm

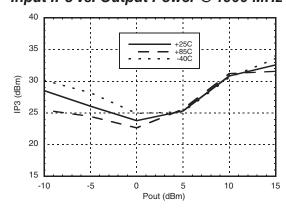


Failsafe Mode - Input Return Loss vs. Temperature

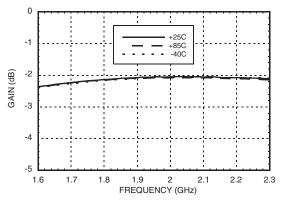


Failsafe Mode -Input IP3 vs. Output Power @ 1900 MHz

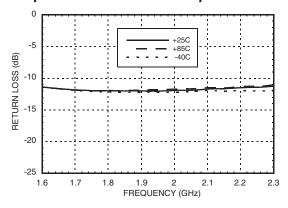
FAILSAFE BYPASS MODE, 1700 - 2200 MHz



Failsafe Mode - Insertion Loss vs. Temperature



Failsafe Mode -Output Return Loss vs. Temperature





HMC669LP3 / 669LP3E

v04.0709



GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

Absolute Maximum Ratings

Drain Bias Voltage (Vdd)	+6 Vdc
Control Voltage (Vctl)	+6 Vdc
RF Input Power (RFIN) LNA Mode Bypass / Fail safe Mode	+5 dBm +20 dBm
Channel Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 10.71 mW/°C above 85 °C)	0.70 W
Thermal Resistance (channel to ground paddle)	93.33 °C/W
Storage Temperature	-65 to +150° C
Operating Temperature	-40 to +85° C
ESD Sensitivity (HBM)	Class 1A



Typical Supply Current vs. Vdd

	Rbias Ω	ldd (mA)			
		Vdd= 3V	Vdd= 5V		
	0	55	95		
	15	49	86		
	47	41	73		
	180 [1]	28	50		

^[1] Recommended maximum Rbias

Truth Table

LNA Mode	Vctl = Vdd = 3 to 5V
Bypass Mode	Vctl= 0V, Vdd = 3 to 5V
Failsafe Mode	VctI = Vdd = N/C

ANALOGDEVICES

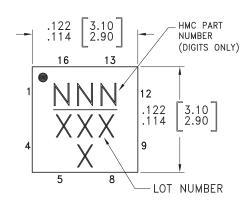
HMC669LP3 / 669LP3E

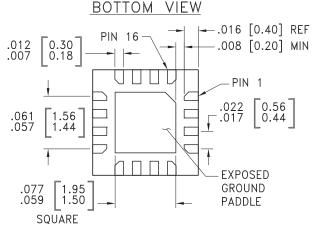
v04.0709

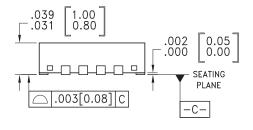


GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

Outline Drawing







NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
 PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC669LP3	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	669 XXXX
HMC669LP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	669 XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX





GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

Pin Descriptions

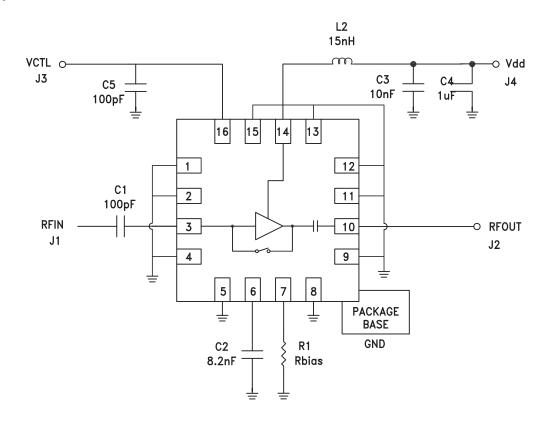
Pin Number	Function	Description	Interface Schematic
1, 2, 5, 8, 11, 12, 13, 15	N/C	These pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
3	RFIN	This pin is DC coupled. Off-chip DC blocking capacitor required.	RFIN O ESD
4, 9	GND	These pins and the exposed ground paddle must be connected to RF/DC ground.	GND =
6	ACG	AC Ground. Attach bypass capacitor per application circuit.	
7	RES	External resistor pin for current control. See table for external resistor value vs. bias current data.	ESD ACG RES
10	RFOUT	This pin is matched to 50 Ohms	RFOUT
14	Vdd	Power Supply voltage pin. External bypass capacitors required.	Vdd ♀
16	Vctl	Control voltage pin for LNA / Bypass Modes. Setting voltage equal to VDD enables LNA Mode. External Bypass capacitor required.	Vctl ESD =





GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

Application Circuit

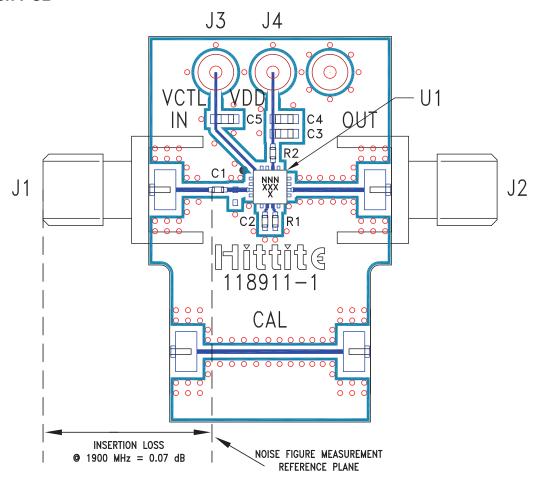






GaAs PHEMT MMIC LNA w/ FAILSAFE BYPASS MODE, 1700 - 2200 MHz

Evaluation PCB



List of Materials for Evaluation PCB 121923 [1]

Item	Description
J1 - J2	PCB Mount SMA Connector
J3 - J4	DC Pin
C1	82 pF Capacitor, 0402 Pkg.
C2	8200 pF Capacitor, 0402 Pkg.
C3	10 nF Capacitor, 0603 Pkg.
C4	1 μF Capacitor, 0603 Pkg.
C5	100 pF Capacitor, 0603 Pkg.
R1	15 Ohm Resistor, 0402 Pkg.
R2	0 Ohm Resistor, 0402 Pkg.
U1	HMC669LP3(E) Amplifier
PCB [2]	118911 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.